

31036 U.S. PTO
09/893588
06/29/01

	Subclass	ISSUE CLASSIFICATION
	Class	

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E. erl SCANNED	PATENT DATE KCC4 Q.A. 004
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APPLICATION NO. 09/893588	CONT/PRIOR	CLASS 257	SUBCLASS 35	ART UNIT 2811	EXAMINER S.27
Takashi Kumamoto					

TITLE
Multi-purpose planarizing/back-grind/pre-underfill arrangements for
bumped wafers and dies

PTO-2040
12/99

ISSUING CLASSIFICATION					
ORIGINAL		CROSS REFERENCE(S)			
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)		
INTERNATIONAL CLASSIFICATION					
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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	(Assistant Examiner) _____ (Date) _____			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____					
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	(Primary Examiner) _____ (Date) _____			ISSUE FEE	
				Amount Due	
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